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COMPONENTS**

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(57) **ABSTRACT**

Methods, systems, and devices for providing computer implemented services are disclosed. To provide the computer implemented services, a data processing system may include hardware components that provide the computer implemented services. Any of the hardware components may have a limited thermal operating range. To retain the temperatures of hardware components within their operating ranges, the data processing system may include heat sinks fitted to the hardware components that are both able to cool and warm the fitted hardware components.

